

What is claimed is:

1. A semiconductor package comprising:

5 a semiconductor chip electrically connected to lead frames;

outer leads protruding from a surface of the semiconductor package, wherein the outer leads are connected to the semiconductor chip through via holes, metal lines and the lead frames connected to the metal lines; and

10 grooves formed at a surface of the semiconductor package, the grooves being connected the metal lines.

2. The semiconductor package of claim 1, wherein the outer leads are disposed opposite to the grooves.

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3. The semiconductor package of claim 1, wherein the semiconductor package is connected to another semiconductor package by inserting the outer leads of the semiconductor package into grooves of another semiconductor package.

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4. A semiconductor package comprising:

a semiconductor chip electrically connected to lead frames;

25 outer wires protruding from a surface of the semiconductor package, wherein the outer wires are connected to the semiconductor chip through via holes, metal lines and

the lead frames connected to the metal lines.

5. The semiconductor package of claim 4, further comprising supporting structures having a predetermined length, the supporting structures being provided on the surface from which the outer wires protrude.

6. The semiconductor package of claim 5, wherein positioning holes are provided on another semiconductor package, the supporting structures being inserted into the positioning holes.

7. The semiconductor package of claim 4, wherein the semiconductor package is connected to another semiconductor package by inserting the outer wires of the semiconductor package into positioning holes of another semiconductor package.

8. The semiconductor package of claim 7, wherein the supporting structures have a length greater than a total length of the interconnected outer wires.

9. The semiconductor package of claim 6, wherein the supporting structures are inserted into the positioning holes.